

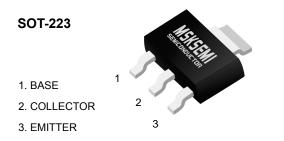


# Product data sheet

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# **PNP Transistors**

- Features
- Collector Current Capability Ic=-4A
- Collector Emitter Voltage VCEO=-140V
- Very low saturation voltages

#### Absolute Maximum Ratings Ta = $25^{\circ}C$

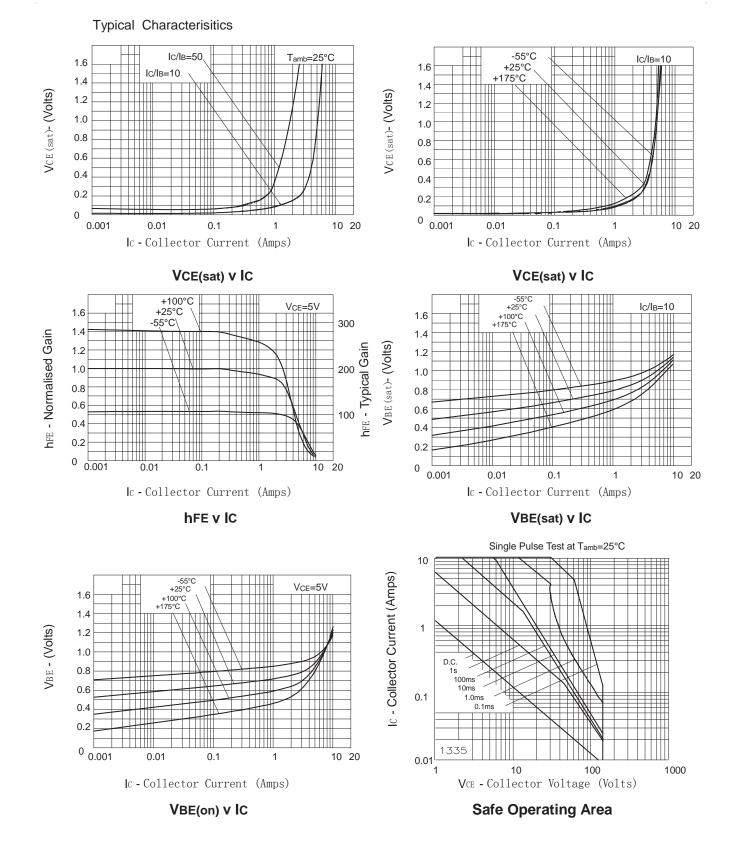
Parameter	Symbol	Rating	Unit	
Collector - Base Voltage	Vсво	-180		
Collector - Emitter Voltage	Vceo	-140	V	
Emitter - Base Voltage	Vebo	-6		
Collector Current - Continuous	lc	-4	A	
Peak Pulse Current	Ісм	-10		
Collector Power Dissipation	Pc	3	W	
Thermal Resistance, Junction to Ambient (Note 1)	Reja	78	°C/W	
Operating and Storage Temperature Range	TJ,Tstg	-55 to 150	°C	

Note 1:For a device mounted with the collector lead on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still airconditions whilst operating in steady-state.

#### Electrical Characteristics Ta = $25^{\circ}$ C

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Collector- base breakdown voltage	Vсво	/сво Іс= -100 μА, Іε=0					
Collector- emitter breakdown voltage	VCER	Ic=-1 μA, Rв ≤ 1kΩ	-180			V	
Collector- emitter breakdown voltage	Vceo	Ic= -10 mA, IB=0	-140				
Emitter - base breakdown voltage	Vebo	IE= -100 μA, IC=0	-6				
Collector-base cut-off current	Ісво	Vcb= -150 V , IE=0			-50	nA	
Collector-base cut-on current		$V_{CB=}$ -150 V , IE=0 , Ta = 100 $^\circ\!\mathrm{C}$			-1	μA	
Collector cut-off current $R < 1k\Omega$	ICER	Vce= -150 V , Ie=0			-50	nA	
Collector cut-off current $R < 1k\Omega$		Vce= -150 V , Ie=0 , Ta = 100 $^\circ\!\mathrm{C}$			-1	μA	
Emitter cut-off current	Іево	VEB= -6V , IC=0			-10	nA	
		Ic=-100 mA, IB=-5 mA			-60		
Collector omitter seturation voltage	VCE(sat)	Ic=-500 mA, IB=-50mA			-120		
Collector-emitter saturation voltage	VCE(sat)	Ic=-1 A, IB=-100mA			-150	mV	
		Ic=-3 A, IB=-300mA			-370		
Base - emitter saturation voltage	VBE(sat)	Ic=-3 A, IB=-300mA			-1110		
Base - emitter turn-on voltage	VBE(on)	Vce= -5V, Ic= -3A			-950		
	hFE	Vce= -5V, Ic= -10mA	100				
DC current gain		Vce=- 5V, Ic= -1 A	100 300		300	]	
		Vce= -5V, Ic= -3 A	75				
		Vce= -5V, Ic= -10 A		10		1	
Switching Times	ton	Iс=-1А, Ів1=-100mА		68		ns	
	toff	IB2=100mA, Vcc=-50V		1030			
Collector output capacitance	Cob	Vcb= -20V,f=1MHz		40		pF	
Transition frequency	fτ	Vce= -10V, Ic= -100mA,f=50MHz		110		MHz	





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FZT955-MS

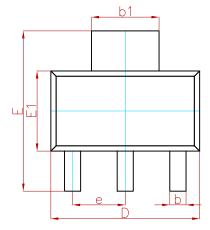
Semiconductor

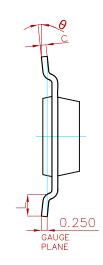
Compiance

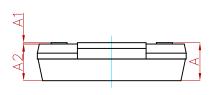




### PACKAGE MECHANICAL DATA

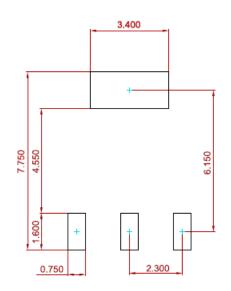






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A		1.800		0.071	
A1	0.020	0.100	0.001	0.004	
A2	1.500	1.700	0.059	0.067	
b	0.660	0.840	0.026	0.033	
b1	2.900	3.100	0.114	0.122	
С	0.230	0.350	0.009	0.014	
D	6.300	6.700	0.248	0.264	
E	6.700	7.300	0.264	0.287	
E1	3.300	3.700	0.130	0.146	
е	2.300(BSC)		0.091(BSC)		
L	0.750		0.030		
θ	0°	10°	0°	10°	

## Suggested Pad Layout



#### Note:

1.Controlling dimension:in millimeters.

- 2.General tolerance:±0.050mm.
- 3.The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
FZT955-MS	SOT-223	1000





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